Package Outline Drawing
Y22.15x15
22 I/O 15mmx15mmx3.6mm Custom HDA Module
Rev 3, 9/18

Notes:
1. All dimensions are in millimeters.
2. All tolerances ±0.10mm, unless otherwise noted.
3. Represents the basic land grid pitch.
4. The total number of smaller I/O pads is 17. All 17 I/O’s are centered in a fixed row and column matrix at 1.0mm pitch BSC.
6. Tolerance for exposed DAP edge location dimension.
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Centerline Position Details for the 5 Exposed DAPs
Bottom View

Dimensional Details for the 5 Exposed PADs
Bottom View
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Suggested Stencil Pattern - 1
Top View

Suggested Stencil Pattern - 2
Top View
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